# HLMP-3707, HLMP-3807, HLMP-3907, HLMP-3750, HLMP-3850, HLMP-3950, HLMP-3960, HLMP-3390, HLMP-3490, HLMP-3590, HLMP-1340, HLMP-1440, HLMP-1540, HLMP-D640, HLMP-K640

T-13/4 (5 mm), T-1 (3 mm), Ultra-Bright LED Lamps

# **Data Sheet**





## Description

These non-diffused lamps out-perform conventional LED lamps. By utilizing new higher intensity material, we achieve superior product performance.

The HLMP-3750/-3390/-1340 Series Lamps are Gallium Arsenide Phosphide on Gallium Phosphide red light emitting diodes. The HLMP-3850/-3490/-1440 Series are Gallium Arsenide Phosphide on Gallium Phosphide yellow light emitting diodes. The HLMP-3950/-3590/-3960/-1540/-D640/-K640 Series Lamps are Gallium Phosphide green light emitting diodes.

## Features

- Improved brightness
- Improved color performance
- Available in popular T-1 and T-1<sup>3</sup>/<sub>4</sub> packages
- New sturdy leads
- IC compatible/low current capability
- Reliable and rugged
- Choice of 3 bright colors High Efficiency Red High Brightness Yellow High Performance Green

## **Applications**

- Lighted switches
- Backlighting front panels
- Light pipe sources
- Keyboard indicators

### **Selection Guide**

		Luminous Intens	sity lv (mcd) @	_			
Package Description	Color	Device HLMP-	Min.	Тур.	Max.	2 <sub>q</sub> 1/2 Degree	Package Outline
T-1 <sup>3</sup> /4	Red	3707-L00xx	90.2	-	-	24	F
		3750	90.2	125.0	-	24	А
		3750-L00xx	90.2	125.0	-	24	А
	Yellow	3807-K00xx	96.2	-	-	24	F
		3850	96.2	140.0	-	24	A
		3850-K00xx	96.2	140.0	-	24	A
		3850-KL0xx	96.2	150.0	294.0	24	A
	Green	3907-K00xx	111.7	-	-	24	F
		3914-K00xx	111.7	-	-	24	D
		3950	111.7	265.0	_	24	A
		3950-K00xx	111.7	265.0	-	24	Α
		3950-LM0xx	170.0	300.0	490.0	24	A
		3960-K0xxx	111.7	265.0	_	24	E
	Emerald Green	D640-E00xx	6.7	21.0	_	24	D
T-1 <sup>3</sup> / <sub>4</sub> Low Profile	Red	3390	35.2	55.0	-	32	В
	Yellow	3490	37.6	55.0	_	32	В
		3490-100xx	37.6	55.0	_	32	В
	Green	3590	43.6	55.0	_	32	В
		3590-100xx	43.6	55.0	-	32	В
T-1	Red	1340	35.2	55.0	_	45	С
		1340-H00xx	8.6	15.0	27.6	45	С
		1340-J00xx	35.2	55.0	-	45	С
		1340-JK0xx	35.2	55.0	112.8	45	С
	Yellow	1440	23.5	45.0	_	45	С
		1440-H00xx	23.5	45.0	_	45	С
		1440-HI0xx	23.5	-	75.2	45	С
		1440-HIB00	23.5	_	75.2	45	С
	Green	1540	27.3	45.0	-	45	С
		1540-H00xx	27.3	45.0	-	45	С
		1540-IJ0xx	43.6	60.0	139.6	45	С
	Emerald Green	K640	4.2	21.0	_	45	C
		K640-D00xx	4.2	21.0	-	45	С
		K640-FGNxx	10.6	20.0	34.0	45	С

### **Package Dimensions**



## **Part Numbering System**



### Absolute Maximum Ratings at $T_A = 25^{\circ}C$

Parameter	Red	Yellow	Green/Emerald Green	Units
Peak Forward Current	90	60	90	mA
Average Forward Current <sup>[1]</sup>	25	20	25	mA
DC Current <sup>[2]</sup>	30	20	30	mA
Transient Forward Current <sup>[3]</sup> (10 μs Pulse)	500	500	500	mA
Reverse Voltage ( $I_R = 100 \ \mu A$ )	5	5	5	V
LED Junction Temperature	110	110	110	°C
Operating Temperature Range	-40 to +100	-40 to +100	-20 to +100	°C
Storage Temperature Range	-40 to +100	-40 to +100	-40 to +100	°C

Notes:

1. See Figure 2 to establish pulsed operating conditions.

2. For Red and Green series derate linearly from 50°C at 0.5 mA/°C. For Yellow series derate linearly from 50°C at 0.2 mA/°C.

3. The transient peak current is the maximum non-recurring peak current the devices can withstand without damaging the LED die and wire bonds.

# Electrical/Optical Characteristics at $T_A = 25^{\circ}C$

			T-1 <sup>3</sup> /4						Test
Symbol	Description	T-1 <sup>3</sup> /4	Low Dome	T-1	Min.	Тур.	Max.	Units	Conditions
λρεακ	Peak	37xx	3390	1340		635		nm	Measurement
	Wavelength	38xx	3490	1440		583			at Peak
		39xx	3590	1540		565			
		D640		K640		558			
$\lambda_d$	Dominant	37xx	3390	1340		626		nm	Note 1
	Wavelength	38xx	3490	1440		585			
		39xx	3590	1540		569			
		D640		K640		560			
$\Delta\lambda^{3}/_{4}$	Spectral Line	37xx	3390	1340		40		nm	
	Halfwidth	38xx	3490	1440		36			
		39xx	3590	1540		28			
		D640		K640		24			
$\tau_{s}$	Speed of	37xx	3390	1340		90		ns	
	Respond	38xx	3490	1440		90			
		39xx	3590	1540		500			
		D640		K640		3100			
С	Capacitance	37xx	3390	1340		11		pF	$V_{F} = 0,$
		38xx	3490	1440		15			f = 1 MHz
		39xx	3590	1540		18			
		D640		K640		35			
$R\theta_{J-PIN}$	Thermal	37xx	3390			210		°C/W	Junction to
	Resistance	38xx	3490			210			Cathode Lead
		39xx	3590			210			
		D640				510			
				1340		290			
				1440		290			
				1540		290			
				K640		290			
V <sub>F</sub>	Forward	37xx	3390	1340	1.5	1.9	2.6	V	$I_F = 20 \text{ mA}$
	Voltage	38xx	3490	1440	1.5	2.1	2.6		(Figure 3)
		39xx	3590	1540	1.5	2.2	3.0		
		D640		K640		2.2	3.0		
V <sub>R</sub>	Reverse	37xx	3390	1340	5.0			V	$I_F = 100 \ \mu A$
	Breakdown	38xx	3490	1440					
	Voltage	39xx	3590	1540					
		D640		K640					
$\eta_v$	Luminous	37xx	3390	1340		145		<u>lumens</u>	Note 2
	Efficacy	38xx	3490	1440		500		watt	
		39xx	3590	1540		595			
		D640		K640		655			

Notes:

1. The dominant wavelength,  $\lambda d$ , is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

2. The radiant intensity, le, in watts per steradian, may be found from the equation  $le = IV/\eta_V$ , where IV is the luminous intensity in candelas and  $\eta_V$  is the luminous efficacy in lumens/watt.

## Red, Yellow, and Green



Figure 1. Relative intensity vs. wavelength.



Figure 2. Maximum tolerable peak current vs. pulse duration. ( $I_{DC}$  MAX as per MAX ratings).



Figure 4. Relative luminous intensity vs. forward current.



Figure 3. Forward current vs. forward voltage.



Figure 5. Relative efficiency (luminous intensity per unit current) vs. peak current.



Figure 6. Relative luminous intensity vs. angular displacement.  $T\text{-}1^3/_4$  lamp.



Figure 7. Relative luminous intensity vs. angular displacement.  $T\text{-}1^{3}\text{/}_{4}$  low profile lamp.



Figure 8. Relative luminous intensity vs. angular displacement. T-1 lamp.

# **Intensity Bin Limits**

	_	Intensity Range (mcd)			
Color	Bin	Min.	Max.		
Red	G	9.7	15.5		
	Н	15.5	24.8		
	1	24.8	39.6		
	J	39.6	63.4		
	К	63.4	101.5		
	L	101.5	162.4		
	Μ	162.4	234.6		
	Ν	234.6	340.0		
	0	340.0	540.0		
	Р	540.0	850.0		
	Q	850.0	1200.0		
	R	1200.0	1700.0		
	S	1700.0	2400.0		
	Т	2400.0	3400.0		
	U	3400.0	4900.0		
	V	4900.0	7100.0		
	W	7100.0	10200.0		
	Х	10200.0	14800.0		
	Υ	14800.0	21400.0		
	Z	21400.0	30900.0		

Maximum tolerance for each bin limit is  $\pm 18\%$ .

# Intensity Bin Limits (continued)

		Intensity Rang	Intensity Range (mcd)		
Color	Bin	Min.	Max.		
Yellow	Н	26.5	42.3		
		42.3	67.7		
	J	67.7	108.2		
	К	108.2	173.2		
	L	173.2	250.0		
	М	250.0	360.0		
	N	360.0	510.0		
	0	510.0	800.0		
	Р	800.0	1250.0		
	Q	1250.0	1800.0		
	R	1800.0	2900.0		
	S	2900.0	4700.0		
	Т	4700.0	7200.0		
	U	7200.0	11700.0		
	V	11700.0	18000.0		
	W	18000.0	27000.0		
Green/	А	1.1	1.8		
Emerald	В	1.8	2.9		
Green	С	2.9	4.7		
	D	4.7	7.6		
	E	7.6	12.0		
	F	12.0	19.1		
	G	19.1	30.7		
	Н	30.7	49.1		
	I	49.1	78.5		
	J	78.5	125.7		
	К	125.7	201.1		
	L	201.1	289.0		
	М	289.0	417.0		
	Ν	417.0	680.0		
	0	680.0	1100.0		
	Р	1100.0	1800.0		
	Q	1800.0	2700.0		
	R	2700.0	4300.0		
	S	4300.0	6800.0		
	Т	6800.0	10800.0		
	U	10800.0	16000.0		
	V	16000.0	25000.0		

		Lambda (nm)		
Color	Cat #	Min.	Max.	
Emerald Green	9	552.5	555.5	
	8	555.5	558.5	
	7	558.5	561.5	
	6	561.5	564.5	
Green	6	561.5	564.5	
	5	564.5	567.5	
	4	567.5	570.5	
	3	570.5	573.5	
	2	573.5	576.5	
Yellow	1	582.0	584.5	
	3	584.5	587.0	
	2	587.0	589.5	
	4	589.5	592.0	
	5	592.0	593.0	
Orange	1	597.0	599.5	
	2	599.5	602.0	
	3	602.0	604.5	
	4	604.5	607.5	
	5	607.5	610.5	
	6	610.5	613.5	
	7	613.5	616.5	
	8	616.5	619.5	

Maximum tolerance for each bin limit is  $\pm 0.5$  nm.

Maximum tolerance for each bin limit is  $\pm 18\%$ .

# **Mechanical Option Matrix**

Mechanical Option Code	Definition
00	Bulk Packaging, minimum increment 500 pcs/bag
01	Tape & Reel, crimped leads, min. increment 1300 pcs/bag for T-1 $^{3}$ / <sub>4</sub> , 1800 pcs/bag for T-1
02	Tape & Reel, straight leads, min. increment 1300 pcs/bag for T-1 <sup>3</sup> / <sub>4</sub> , 1800 pcs/bag for T-1
A1	T-1, Right Angle Housing, uneven leads, minimum increment 500 pcs/bag
A2	T-1, Right Angle Housing, even leads, minimum increment 500 psc/bag
B1	T-1 <sup>3</sup> / <sub>4</sub> , Right Angle Housing, uneven leads, minimum increment 500 pcs/bag
B2	T-1 <sup>3</sup> / <sub>4</sub> , Right Angle Housing, even leads, minimum increment 500 psc/bag
BJ	T-1, Tape & Reel, straight leads, minimum increment 2000 pcs/bag
EG	Ammo Pack, straight leads in 5 K increment
FH	Devices that require inventory control and 2 $I_v$ bin select
VR	Ammo Pack, crimped leads, min. increment 2 k for T-1 $^{3}/_{4}$ and T-1

Note:

All categories are established for classification of products. Products may not be available in all categories. Please contact your local Avago representative for further clarification/information.

## **Precautions:**

## Lead Forming

- The leads of an LED lamp may be preformed or cut to length prior to insertion and soldering into PC board.
- If lead forming is required before soldering, care must be taken to avoid any excessive mechanical stress induced to LED package. Otherwise, cut the leads of LED to length after soldering process at room temperature. The solder joint formed will absorb the mechanical stress of the lead cutting from traveling to the LED chip die attach and wirebond.
- It is recommended that tooling made to precisely form and cut the leads to length rather than rely upon hand operation.

### **Soldering Conditions**

- Care must be taken during PCB assembly and soldering process to prevent damage to LED component.
- The closest LED is allowed to solder on board is 1.59 mm below the body (encapsulant epoxy) for those parts without standoff.
- Recommended soldering conditions:

Wave Soldering	Dipping	Manual Solder
Pre-heat Temperature	105 °C Max.	-
Pre-heat Time	30 sec Max.	_
Peak Temperature	250 °C Max.	260 °C Max.
Dwell Time	3 sec Max.	5 sec Max.

- Wave soldering parameter must be set and maintained according to recommended temperature and dwell time in the solder wave. Customer is advised to periodically check on the soldering profile to ensure the soldering profile used is always conforming to recommended soldering condition.
- If necessary, use fixture to hold the LED component in proper orientation with respect to the PCB during soldering process.
- Proper handling is imperative to avoid excessive thermal stresses to LED components when heated. Therefore, the soldered PCB must be allowed to cool to room temperature, 25°C, before handling.
- Special attention must be given to board fabrication, solder masking, surface plating and lead holes size and component orientation to assure solderability.
- Recommended PC board plated through hole sizes for LED component leads:

LED Component Lead Size	Diagonal	Plated Through Hole Diameter
0.457 x 0.457 mm	0.646 mm	0.976 to 1.078 mm
(0.018 x 0.018 inch)	(0.025 inch)	(0.038 to 0.042 inch)
0.508 x 0.508 mm	0.718 mm	1.049 to 1.150 mm
(0.020 x 0.020 inch)	(0.028 inch)	(0.041 to 0.045 inch)

Note: Refer to application note AN1027 for more information on soldering LED components.



Figure 8. Recommended wave soldering profile.

For product information and a complete list of distributors, please go to our web site: www.avagotech.com

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